EAD card (relocatable) deng.ya.nuo@gmail.com

### CAREER PATH

ASIC expert with 15+ years of experience and a proven record working with embedded system (linux/RTOS), and digital & analogy circuit design

### Professional Qualification

Licensed and Certified Electronic Engineer, China, 2008

### **EXPERIENCE**

### C-MATRIXTECH CO.LTD., Zhuhai, China

Integrated Circuit Engineer, Dec 2017 - Feb 2019

- \* Verilog + FPGA for self-powered MCU SOC chips for iPhone Lightning cables.
- \* MCU debug; Port C from Assembly for the 13-bits MCU (PIC); Mixed (Analog) circuit design.
- \* Xilinx autobuild & remote download firmware platform for remote team work.

## VIOMI CO.LTD., Foshan, China

Software (Firmware) Engineer, May 2017 - Oct 2017

- \* Linux driver for the WiFi chip; Speech Recognition & Synthesis App for Linux.
- \* UART, GPIO, SPI, NAND flash, TCP/UDP/IP, WiFi debug. Buildroot.

### BLUEWAY CO.LTD., Huizhou, China

Software (Firmware) Engineer, May 2016 - Apr 2017

- \* FreeRTOS port to STM32 for for AI mowers. Ingenic X1000E USB OnTheGo (OTG).
- \* Mathematica to optimize the walking path of the mowers (AI path planning).

### ADON CO.LTD., Foshan, China

Software (Firmware) Engineer, Oct 2013 - Dec 2015

- \* Linux driver & app for the Homepod (iPhone WiFi speaker/charger). Bootloader porting.
- \* Qualcomm AR9331: WiFi, I2S, UART, SPI, GPIO. OpenWRT.

# SKYIT SOFTWARE CO.LTD., Shunde, China $Software\ Engineer,\ Dec\ 2011$ - $Jul\ 2013$

- \* Developed the first meal order App for Android in China
- \* Windows App by C#; MySQL API by C

### VBRIDGE MICROSYSTEM INC, San Jose, CA, USA.

Digital Integrated Circuit Engineer, Apr 2005 - May 2008

- \* IP cores of security engineer (TLS): AES, DES, 3DES, MD5, SHA1, CRC; 5-bits MCU core.
- \* All IP cores tapout in a dual-MIPS SOC Chip. Bootloader porting. NC(Incisive) + Verdi.
- \* UDP data package sender/receiver by Altera. OmniVision Image sensor data modified by Altera.
- \* Linux/VxWorks board support package(BSP): UART, I2C, SPI, SDIO. OpenOCD for jtag.

### **EDUCATION**

Xi'an university of technology, China

MSc in Microelectronics & Solid State Electronics, 2005

BSc in Microelectronics Technology, 2002

Yuba College, ESL Class, 2021; Evergreen Valley College, ESL Class, 2020

\* C, Verilog, Vim, Bash, Awk, Sed, Perl, Golang, Gnumake, Git

\* Linux / FreeRTOS driver; UART, SPI, I2C, I2S, USB OnTheGo, WiFi hostapd/wpa supplicant

### Personal Characteristics

I can work well individually or with team members. I have been working as a team member or a team leader. I find satisfications in seeing projects completed.

### Referrals

Dan Teuthorn, Teledyne Microwave, VP Engineer, (408)421-7303, Den.Teuthorn@teledyne.com Tang Shanqiang, Cadence, Principal Application Engineer, +65-9054-6301, ansent@cadence.com Stephen Fung, Qualcomm, Semicondutor Engineer, (408)338-5175, stephen@thepoint.church